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### Power MOSFET, Single P-Channel

–60 V, –100 A, 7.7 m $\Omega$ 

#### **Features**

- Small Footprint (5 x 6 mm) for Compact Design
- Low R<sub>DS(on)</sub> to Minimize Conduction Losses
- NVMFS5A160PLZWF: Wettable Flank Option for Enhanced Optical Inspection
- AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

# **SPECIFICATION MAXIMUM RATINGS** ( $T_J = 25^{\circ}C$ unless otherwise noted) (Notes 1, 2, 3)

Symbol	Parameter			Value	Unit
V <sub>DSS</sub>	Drain to Source Voltage			-60	V
V <sub>GS</sub>	Gate to Source Voltage			±20	V
I <sub>D</sub>	Continuous Drain, Current R <sub>0</sub> JC, (Notes 1, 3)	Steady State	T <sub>C</sub> = 25°C	-100	Α
P <sub>D</sub>	Power Dissipation $R_{\theta JC}$ (Note 1)	olale	T <sub>C</sub> = 25°C	200	W
I <sub>D</sub>	Continuous Drain: Current $R_{\theta JA}$ (Notes 1, 2, 3)	Steady State	T <sub>A</sub> = 25°C	-15	A
P <sub>D</sub>	Power Dissipation R <sub>θJA</sub> (Note 1, 2)	Oldic	T <sub>A</sub> = 25°C	3.8	W
I <sub>DP</sub>	Pulsed Drain Current	PW ≤ 10 duty cycle		-400	Α
T <sub>J</sub> , T <sub>STG</sub>	Operating Junction and Storage Temperature			–55 to +175	°C
I <sub>S</sub>	Source Current (Body Diode)			-100	Α
E <sub>AS</sub>	Single Pulse Drain to Source Avalanche Energy (L= 1.0 mH, I <sub>L(pk)</sub> = -26 A)			335	mJ
T <sub>L</sub>	Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			260	°C

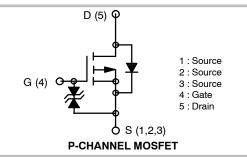
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.



#### ON Semiconductor®

#### www.onsemi.com

V <sub>DSS</sub>	R <sub>DS(ON)</sub> MAX	I <sub>D</sub> MAX
-60 V	7.7 mΩ @ –10 V	-100 A
	10.5 mΩ @ -4.5 V	





DFN5 (SO-8FL)

#### **MARKING DIAGRAM**



XXXXXX = Specific Device Code

5A160L(NVMFS5A160PLZ) 160LWF(NVMFS5A160PLZWF)

A = Assembly Location

Y = Year W = Work Week

ZZ = Lot Traceability

#### **ORDERING INFORMATION**

See detailed ordering and shipping information on page 7 of this data sheet.

#### THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
$R_{ heta JC}$	Junction to Case Steady State		°C/W
$R_{\theta JA}$	Junction to Ambient Steady State (Note 3)		

- The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
- 2. Surface mounted on FR4 board using a 650 mm<sup>2</sup>, 2 oz. Cu pad.
- 3. Maximum current for pulses as long as 1 second is higher but is dependent on pulse duration and duty cycle.

### **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub> = 25°C unless otherwise noted)

Symbol	Parameter	Test Condition		Min	Тур	Max	Unit
OFF CHARA	ACTERISTICS			•	•		
V <sub>(BR)DSS</sub>	Drain to Source Breakdown Voltage	$I_D = -1$ mA, $V_{GS} = 0$ V		-60			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS} = -60 \text{ V}, V_{GS} = 0 \text{ V}$	T <sub>J</sub> = 25°C			-1.0	μΑ
			T <sub>J</sub> = 100°C (Note 4)			-100	μΑ
I <sub>GSS</sub>	Gate to Source Leakage Current	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0 \text{ V}$				±10	μΑ
ON CHARA	CTERISTICS (Note 5)						
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = -10 \text{ V}, I_{D} = -1 \text{ mA}$		-1.2		-2.6	V
R <sub>DS(on)</sub>	Drain to Source On Resistance	V <sub>GS</sub> = -10 V	I <sub>D</sub> = -50 A		5.8	7.7	0
		V <sub>GS</sub> = -4.5 V	I <sub>D</sub> = -50 A		7.3	10.5	mΩ
9 <sub>FS</sub>	Forward Transconductance	$V_{DS} = -10 \text{ V}, I_D = -50 \text{ A}$	•		119		S
CHARGES,	CAPACITANCES & GATE RESISTA	ANCE					
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> = 0 V, f = 1 MHz			7700		pF
C <sub>oss</sub>	Output Capacitance	$V_{DS} = -20 \text{ V},$			720		
C <sub>rss</sub>	Reverse Transfer Capacitance				540		
Q <sub>g(tot)</sub>	Total Gate Charge	V <sub>GS</sub> = -10 V, I <sub>D</sub> = -50 A			160		
Q <sub>gs</sub>	Gate to Source Charge	$V_{DS} = -36 \text{ V},$			24		nC
Q <sub>gd</sub>	Gate to Drain Charge	1			45		
SWITCHING	CHARACTERISTICS (Note 6)						
t <sub>d(on)</sub>	Turn-On Delay Time	$V_{DS} = -36 \text{ V}, I_D = -50 \text{ A},$			50		
t <sub>r</sub>	Rise Time	$V_{GS} = -10 \text{ V},$ $R_G = 50 \Omega$			690		
t <sub>d(off)</sub>	Turn-Off Delay Time				645		ns
t <sub>f</sub>	Fall Time				643		
DRAIN-SOU	RCE DIODE CHARACTERISTICS						
$V_{SD}$	Forward Diode Voltage	V <sub>GS</sub> = 0 V, I <sub>S</sub> = -50 A			-0.83	-1.5	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> = 0 V, I <sub>S</sub> = -50 A			93		ns
Q <sub>rr</sub>	Reverse Recovery Charge	di/dt = 100 A/μs			218		nC

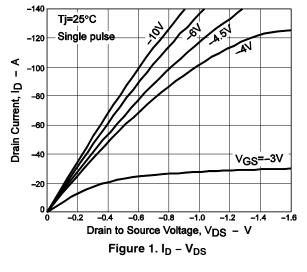
Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. The maximum value is specified by design at T<sub>J</sub> = 100 °C. Product is not tested to this condition in production.

5. Pulse Test: pulse width ≤ 300μs, duty cycle ≤ 2%.

6. Switching characteristics are independent of operating junction temperatures.

#### **TYPICAL CHARACTERISTICS**



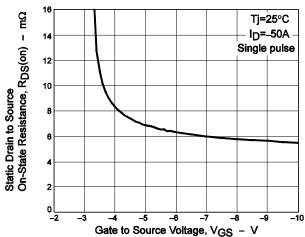


Figure 3. R<sub>DS(on)</sub> - V<sub>GS</sub>

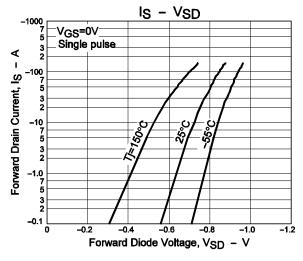
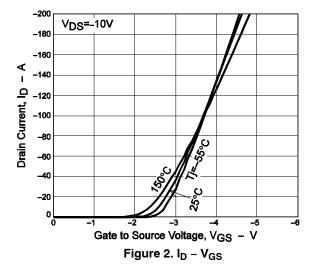


Figure 5. I<sub>S</sub> - V<sub>SD</sub>



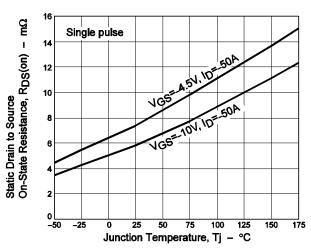


Figure 4. R<sub>DS(on)</sub> - T<sub>J</sub>

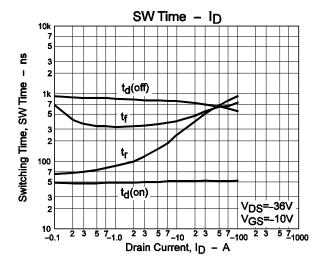


Figure 6. SW Time - ID

#### **TYPICAL CHARACTERISTICS**

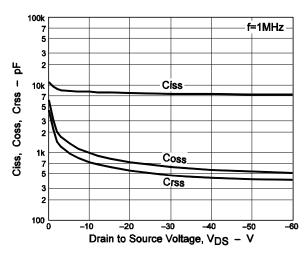


Figure 7. Ciss, Coss, Crss - V<sub>DS</sub>

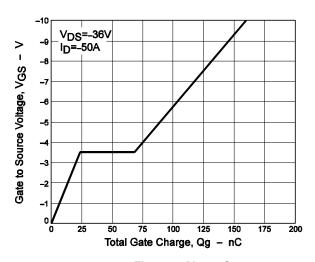


Figure 8. V<sub>GS</sub> - Qg

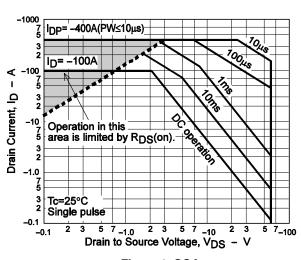


Figure 9. SOA

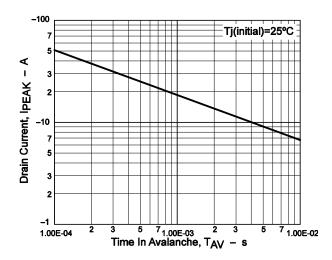


Figure 10. I<sub>PEAK</sub> - T<sub>AV</sub>

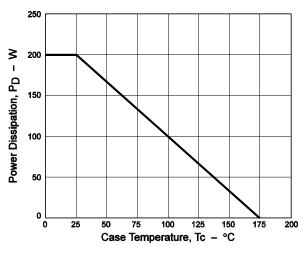


Figure 11. P<sub>D</sub> - T<sub>C</sub>

#### **TYPICAL CHARACTERISTICS**

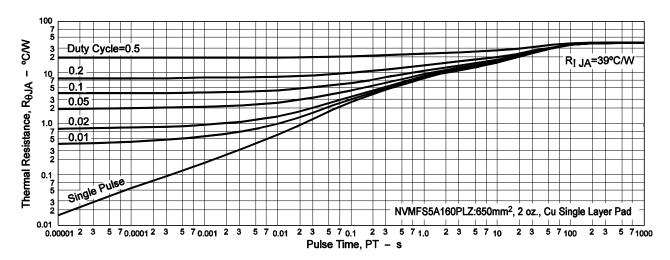
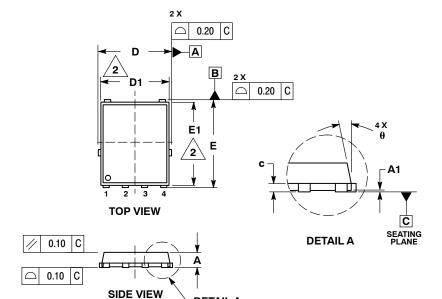


Figure 12.  $R_{\theta JA}$  – Pulse Time

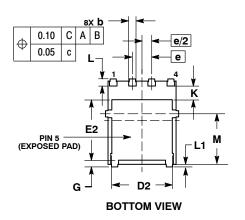
#### DFN5 5x6, 1.27P (SO-8FL) CASE 488AA ISSUE M



**DETAIL A** 

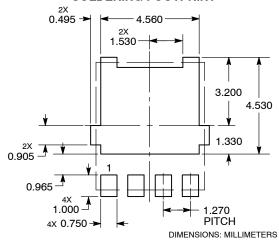
- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. DIMENSION DI AND E1 DO NOT INCLUDE MOLD FLASH PROTRUSIONS OR GATE BURRS.

	MILLIMETERS			
DIM	MIN	NOM	MAX	
Α	0.90	1.00	1.10	
A1	0.00		0.05	
b	0.33	0.41	0.51	
С	0.23	0.28	0.33	
D	5.00	5.15	5.30	
D1	4.70	4.90	5.10	
D2	3.80	4.00	4.20	
E	6.00	6.15	6.30	
E1	5.70	5.90	6.10	
E2	3.45	3.65	3.85	
е		1.27 BSC		
G	0.51	0.575	0.71	
K	1.20	1.35	1.50	
L	0.51	0.575	0.71	
L1	0.125 REF			
М	3.00	3.40	3.80	
θ	0 °		12 °	



STYLE 1: PIN 1. SOURCE 2. SOURCE 3. SOURCE 4. GATE 5. DRAIN

#### **RECOMMENDED SOLDERING FOOTPRINT\***



#### **ORDERING INFORMATION**

Device	Marking	Package	Shipping (Qty / Packing) <sup>†</sup>
NVMFS5A160PLZT1G	5A160L	DFN5 5x6, 1.27P (SO-8FL) (Pb-Free)	1.500 / Tape & Reel
NVMFS5A160PLZWFT1G	160LWF	DFN5 5x6, 1.27P (SO-8FL) (Pb-Free, Wettable Flanks)	1.500 / Tape & Reel
NVMFS5A160PLZT3G	5A160L	DFN5 5x6, 1.27P (SO-8FL) (Pb-Free)	5.000 / Tape & Reel
NVMFS5A160PLZWFT3G	160LWF	DFN5 5x6, 1.27P (SO-8FL) (Pb-Free, Wettable Flanks)	5.000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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